

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

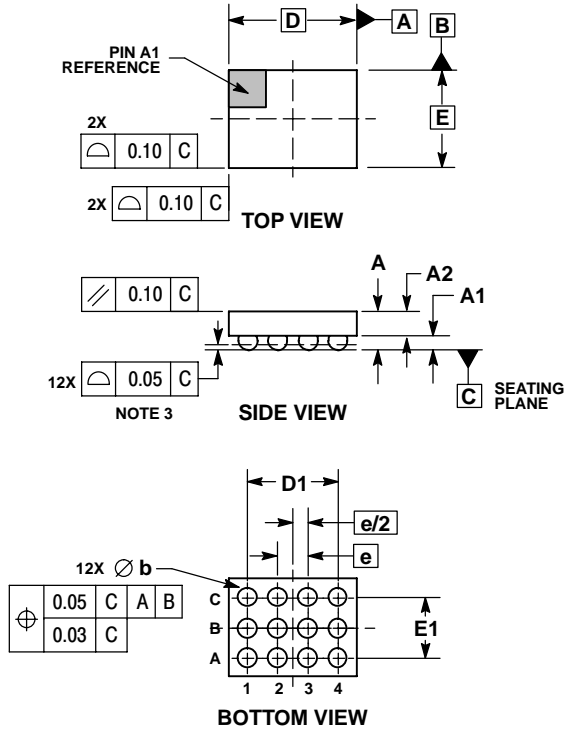
ON Semiconductor®



12 PIN FLIP-CHIP, 2.02x1.54, 0.5P  
CASE 499AU-01  
ISSUE O

DATE 19 MAR 2007

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.66
A1	0.21	0.27
A2	0.33	0.39
b	0.29	0.34
D	2.02 BSC	
D1	1.50 BSC	
E	1.54 BSC	
E1	1.00 BSC	
e	0.50 BSC	

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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	12 PIN FLIP-CHIP, 2.02 X 1.54, 0.5P	<b>PAGE 1 OF 2</b>

